

KONNEKT™ KC-LINK™ for High-Efficiency, High-Density Power Applications (Commercial Grade)



Overview

KEMET's KONNEKT™ KC-LINK™ surface mount capacitors are designed for high-efficiency and high-density power applications. KONNEKT uses an innovative Transient Liquid Phase Sintering (TLPS) material to create a surface mount multi-chip solution for high density packaging. By utilizing KEMET's robust and proprietary COG base metal electrode (BME) dielectric system, these capacitors are well suited for power converters, inverters, snubbers, and resonators where high efficiency is a primary concern.

KONNEKT KC-LINK enables a low-loss, low-inductance package capable of handling extremely high ripple currents with no change in capacitance versus DC voltage, and negligible change in capacitance versus

temperature. With an operating temperature range up to 150°C, KONNEKT KC-LINK capacitors can be mounted close to fast switching semiconductors in high power density applications, which require minimal cooling. KONNEKT KC-LINK dielectric technology also exhibits high mechanical robustness compared to other dielectric technologies, allowing the capacitor to be mounted without the use of metal frames.

KONNEKT KC-LINK can also be mounted in a low-loss orientation to further increase its power handling capability. The low-loss orientation lowers ESR (Effective Series Resistance) and ESL (Effective Series Inductance) which increases ripple current handling capability.

Benefits

- Extremely high-power density and ripple current capability
- Extremely low equivalent series resistance (ESR)
- Extremely low equivalent series inductance (ESL)
- Low-loss orientation option for higher current handling capability
- Operating temperature range of -55°C to +150°C
- High frequency operation (> 10 MHz)
- No capacitance shift with voltage
- No piezoelectric noise
- High thermal stability
- Surface mountable using standard MLCC reflow profiles
- RoHS compliant and Pb-free

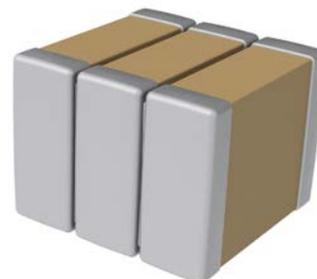
Applications

- Wide bandgap (WBG), silicon carbide (SiC) and gallium nitride (GaN) systems
- Data centers
- EV/HEV (drive systems, charging)
- LLC resonant converters
- Switched tank converters
- Wireless charging systems
- Photovoltaic systems
- Power converters
- Inverters
- DC link
- Snubber

Standard



Low Loss



Electrical Parameters/Characteristics

Item	Parameters/Characteristics	
Operating temperature range	-55°C to +150°C	
Capacitance change with reference to +25°C and 0 VDC applied (TCC)	±30 PPM/°C	
Aging rate (maximum % capacitance loss/decade hour)	0%	
¹ Dielectric Withstanding Voltage (DWV)	Rated Voltage	DWV
	500 V	150% of rated voltage
	650 V	130% of rated voltage
	≥ 1,000 V	120% of rated voltage
	(5±1 seconds and charge/discharge not exceeding 50 mA)	
² Dissipation Factor (DF) Maximum Limit at 25°C	0.1%	
³ Insulation Resistance (IR) Minimum Limit at 25°C	1,000 - MΩ - μF or 100 GΩ (500 VDC applied for 120±5 seconds at 25°C)	

¹ DWV is the voltage a capacitor can withstand (survive) for a short period of time. It exceeds the nominal and continuous working voltage of the capacitor.

² Capacitance and dissipation factor (DF) measured under the following conditions:

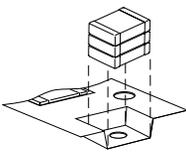
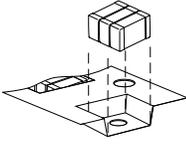
1 kHz ±50 Hz and 1.0 ±0.2 V_{rms}

³ To obtain IR limit, divide MΩ - μF value by the capacitance and compare to GΩ limit. Select the lower of the two limits.

Ordering Information

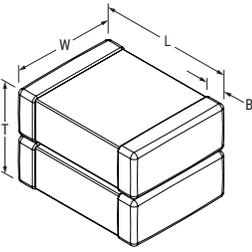
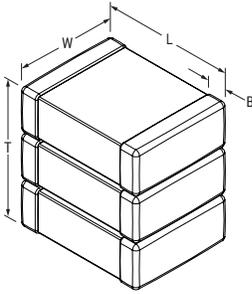
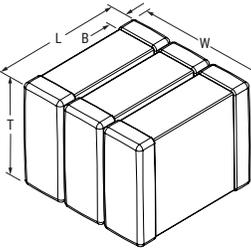
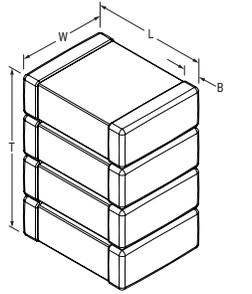
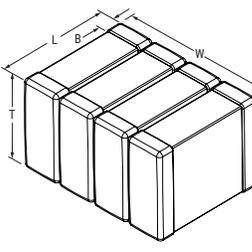
CKC	33	C	884	K	C	G	L	C	XXXX
Series	Case Size (L" x W")	Specification/ Series	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (V)	Dielectric	Subclass Designation	Termination Finish	Orientation and Packaging (Suffix/C-Spec)
CKC = KC-LINK	33 = 3640	C = Standard	Two single digits and number of zeros.	K = ±10%	C = 500 V W = 650 V D = 1,000 V E = 1,200 V J = 1,700 V	G = COG	L = KONNEKT	C = 100% matte Sn	See "Packaging C-Spec Ordering Options Table"

Orientation and Packaging (Suffix/C-Spec) Options Table

Mounting Orientation ¹		Tape and Reel Illustration	Packaging Type	Packaging/Grade Ordering Code (C-Spec)
Standard			7" Reel/Unmarked	TU (7800)
			13" Reel/Unmarked	7210
Low Loss			7" Reel/Unmarked	7805
			13" Reel/Unmarked	7810

¹ Orientation refers to the positioning of the KONNEKT capacitors in the Tape and Reel pockets. This allows pick and place machines to place capacitors on the PCB in the correct orientation.

Dimensions – Millimeters (Inches)

Standard Mounting 2 Chips	Standard Mounting 3 Chips	Low Loss Mounting 3 Chips	Standard Mounting 4 Chips	Low Loss Mounting 4 Chips
				

Number of Chips	Mounting	EIA SIZE CODE	METRIC SIZE CODE	L LENGTH	W WIDTH	T THICKNESS	B BANDWIDTH	Mounting Technique
2	Standard	3640	9210	9.30 (0.366) ±0.60 (0.024)	10.20 (0.402) +/-0.40 (0.016)	5.10 (0.201) +/-0.40 (0.016)	1.27 (0.050) ±0.40 (0.016)	Solder Reflow Only
3	Standard				10.20 (0.402) +/-0.40 (0.016)	7.70 (0.303) +/-0.60 (0.24)		
	Low Loss				7.70 (0.303) +/-0.60 (0.24)	10.20 (0.402) +/-0.40 (0.016)		
4	Standard				10.20 (0.402) +/-0.40 (0.016)	10.30 (0.405) +/-0.80 (0.031)		
	Low Loss				10.30 (0.405) +/-0.80 (0.031)	10.20 (0.402) +/-0.40 (0.016)		

Table 1A - Product Ordering Codes and Ratings

Capacitance	Capacitance Code	Number of Chips	Case Size	3640				
			Voltage Code	C	W	D	E	J
			Rated Voltage (VDC)	500	650	1000	1200	1700
			Capacitance Tolerance	Product Availability				
44 nF	443	2	K					•
66 nF	663	3	K					•
88 nF	883	4	K					•
94 nF	943	2	K				•	
140 nF	144	3	K				•	
200 nF	204	4	K				•	
110 nF	114	2	K			•		
170 nF	174	3	K			•		
220 nF	224	4	K			•		
300 nF	304	2	K		•			
450 nF	454	3	K		•			
600 nF	604	4	K		•			
440 nF	444	2	K	•				
660 nF	664	3	K	•				
880 nF	884	4	K	•				

These products are protected under one or more of the following Patents: US Pat. No. 9,472,342B2, EP Pat. No. 2923366B1, JP Pat. No. 06091639B2, TW Pat. No. 579873B, US Pat. No. 10,068,707B2.

Table 1B – Chip Thickness/Tape & Reel Packaging Quantities

Case Size	Number of Chips	Orientation	Plastic Quantity	
			7" Reel	13" Reel
3640	2	Standard	125	575
		Standard	75	375
	3	Low Loss	50	275
		Standard	50	225
		Low Loss	50	225

Table 2 – Performance & Reliability: Test Methods and Conditions (Commercial Only)

Stress	Reference	Test or Inspection Method
Terminal Strength	JIS-C-6429	Appendix 1, Note: Force of 1.8 kg for 60 seconds
Board Flex	JIS-C-6429	Appendix 2, Note: 3.0 mm (minimum)
Solderability	KEMET Custom Test	1. Board shear - SAC305 solder. Shear force of 1.8 kg (minimum)
		2. Wetting balance - IEC 60068-2-69
Temperature Cycling	JESD22 Method JA-104	1,000 cycles (-55°C to +150°C), measurement at 24 hours ±4 hours after test conclusion
Biased Humidity	MIL-STD-202 Method 103	Load Humidity: 1,000 hours 85°C/85% RH and 200VDC. Add 100 K ohm resistor. Measurement at 24 hours ±4 hours after test conclusion.
		Low Volt Humidity: 1,000 hours 85°C/85%RH and 1.5 V. Add 100 K ohm resistor. Measurement at 24 hours ±4 hours after test conclusion.
High Temperature Life	MIL-STD-202 Method 108/EIA-198	1,000 hours at 150°C with 1.0 X rated voltage applied
Storage Life	MIL-STD-202 Method 108	150°C, 0 VDC, for 1,000 hours.
Vibration	MIL-STD-202 Method 204	5 g for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8" x 5" PCB 0.031" thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10 – 2,000 Hz.
Mechanical Shock	MIL-STD-202 Method 213	Method 213: Figure 1, Condition F Method 204: 5gs for 20 min, 12 cycles
Resistance to Solvents	MIL-STD-202 Method 215	Add aqueous wash chemical, OKEM Clean or equivalent

Environmental Compliance



Lead (Pb)-free, RoHS, and REACH compliant without exemptions.

Table 3 – KONNEKT Land Pattern Design Recommendations per IPC-7351 (mm)

Chip Number	Orientation	EIA SIZE CODE	METRIC SIZE CODE	Median (Nominal) Land Protrusion				
				C	Y	X	V1	V2
2	Standard	3640	9210	4.35	1.5	10.6	10.7	11.1
3	Standard			4.35	1.5	10.6	10.7	11.1
	Low Loss			4.35	1.5	8.3	10.7	8.8
4	Standard			4.35	1.5	10.6	10.7	11.1
	Low Loss	4.35	1.5	10.7	10.7	11.2		

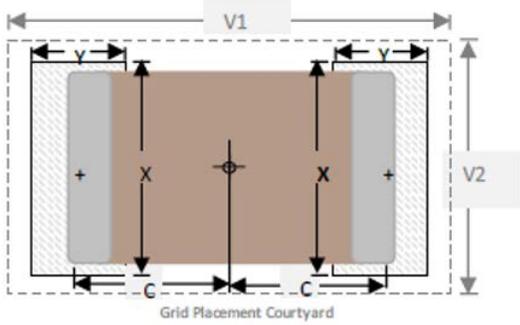
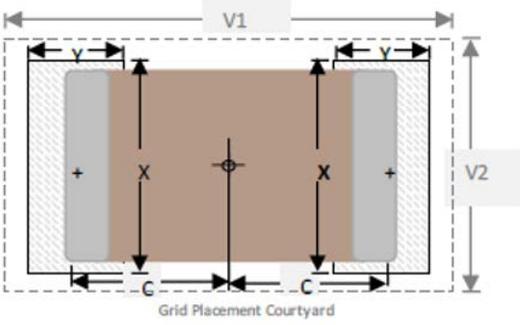
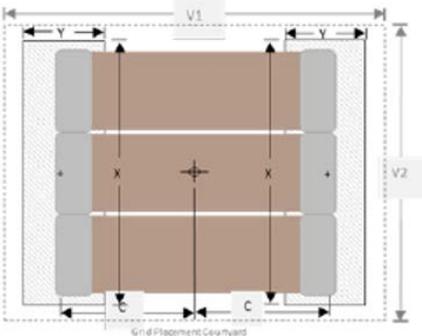
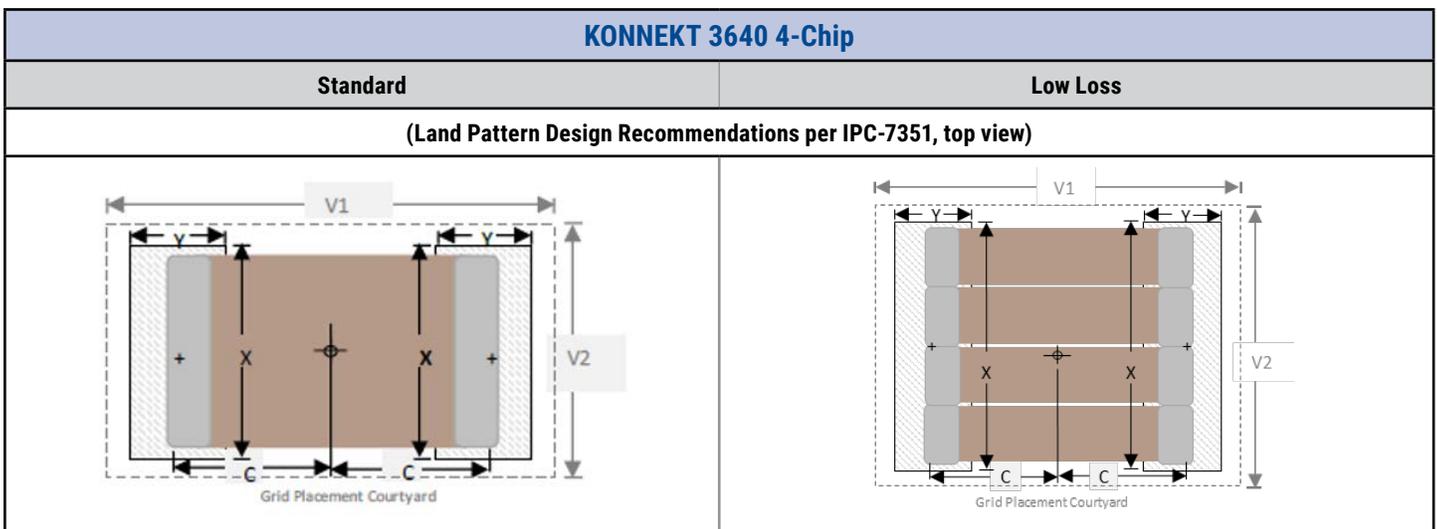
KONNEKT 3640 2-Chip	
Standard	Low Loss
(Land Pattern Design Recommendations per IPC-7351, top view)	
 <p style="text-align: center;">Grid Placement Courtyard</p>	<p>Not available in Low Loss</p>
KONNEKT 3640 3-Chip	
Standard	Low Loss
(Land Pattern Design Recommendations per IPC-7351, top view)	
 <p style="text-align: center;">Grid Placement Courtyard</p>	 <p style="text-align: center;">Grid Placement Courtyard</p>

Table 3 – KONNEKT Land Pattern Design Recommendations per IPC-7351 (mm) cont.

Chip Number	Orientation	EIA SIZE CODE	METRIC SIZE CODE	Median (Nominal) Land Protrusion				
				C	Y	X	V1	V2
2	Standard	3640	9210	4.35	1.5	10.6	10.7	11.1
3	Standard			4.35	1.5	10.6	10.7	11.1
	Low Loss			4.35	1.5	8.3	10.7	8.8
4	Standard			4.35	1.5	10.6	10.7	11.1
	Low Loss	4.35	1.5	10.7	10.7	11.2		

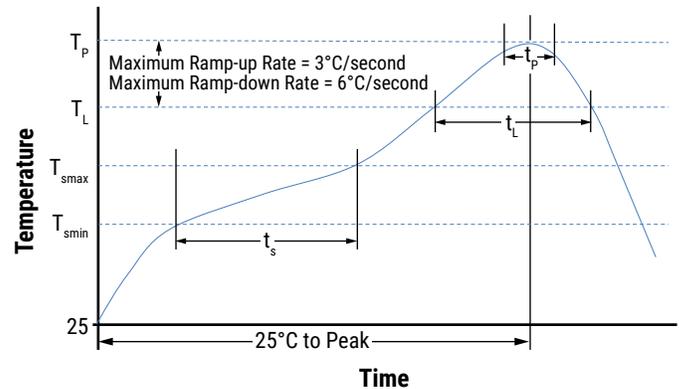


Soldering Process

Recommended Reflow Soldering Profile

KEMET's KONNEKT family of high density surface mount multilayer ceramic capacitors (SMD MLCCs) are compatible with convection and IR reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three reflow passes at these conditions.

Profile Feature	Termination Finish
	100% matte Sn
Preheat/Soak	
Temperature Minimum (T_{Smin})	150°C
Temperature Maximum (T_{Smax})	200°C
Time (t_s) from T_{Smin} to T_{Smax}	60 – 120 seconds
Ramp-Up Rate (T_L to T_p)	3°C/second maximum
Liquidous Temperature (T_L)	217°C
Time Above Liquidous (t_L)	60 – 150 seconds
Peak Temperature (T_p)	260°C
Time Within 5°C of Maximum Peak Temperature (t_p)	30 seconds maximum
Ramp-Down Rate (T_p to T_L)	6°C/second maximum
Time 25°C to Peak Temperature	8 minutes maximum



Note: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.

Hand Soldering and Removal of KONNEKT Capacitors

The preferred method of attachment for KEMET's KONNEKT™ Capacitors is IR or convection reflow where temperature, time and air flow are well controlled.

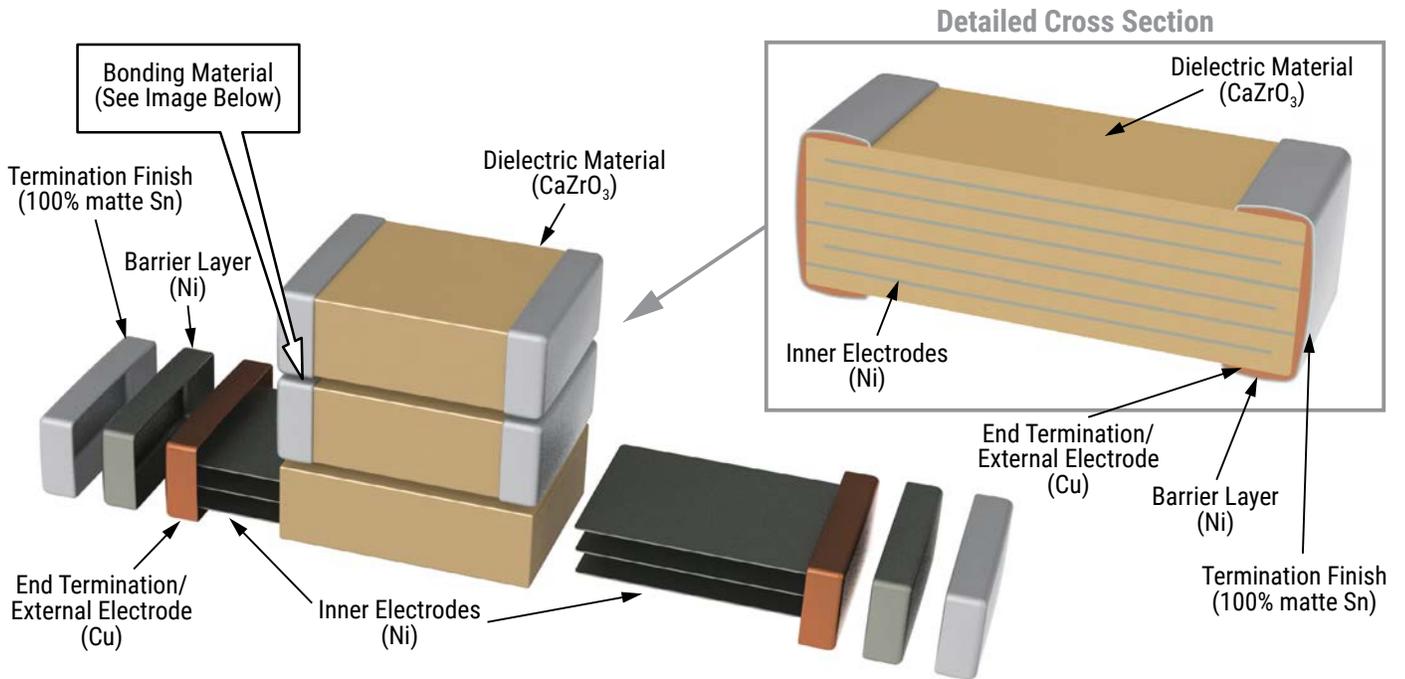
However, it is understood that the manual attachment of KONNEKT™ capacitors is necessary for prototype and lab testing. In these instances, care must be taken not to introduce excessive temperature gradients in the KONNEKT™ part type that may lead to cracking in the ceramic or separation of the TLPS material.

Please see KEMET's KONNEKT™ Soldering Guidelines ([LINK](#))

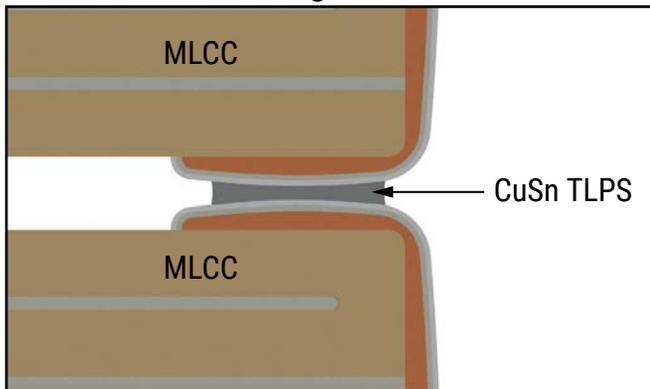
Storage & Handling

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature – reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. In addition, temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years upon receipt.

Construction



Bonding Material



Tape & Reel Packaging Information

KEMET offers multilayer ceramic chip capacitors packaged in 8, 12, 16 and 24 mm tape on 7" and 13" reels in accordance with EIA Standard 481. This packaging system is compatible with all tape-fed automatic pick and place systems. See Table 1B for details on reeling quantities for commercial chips.

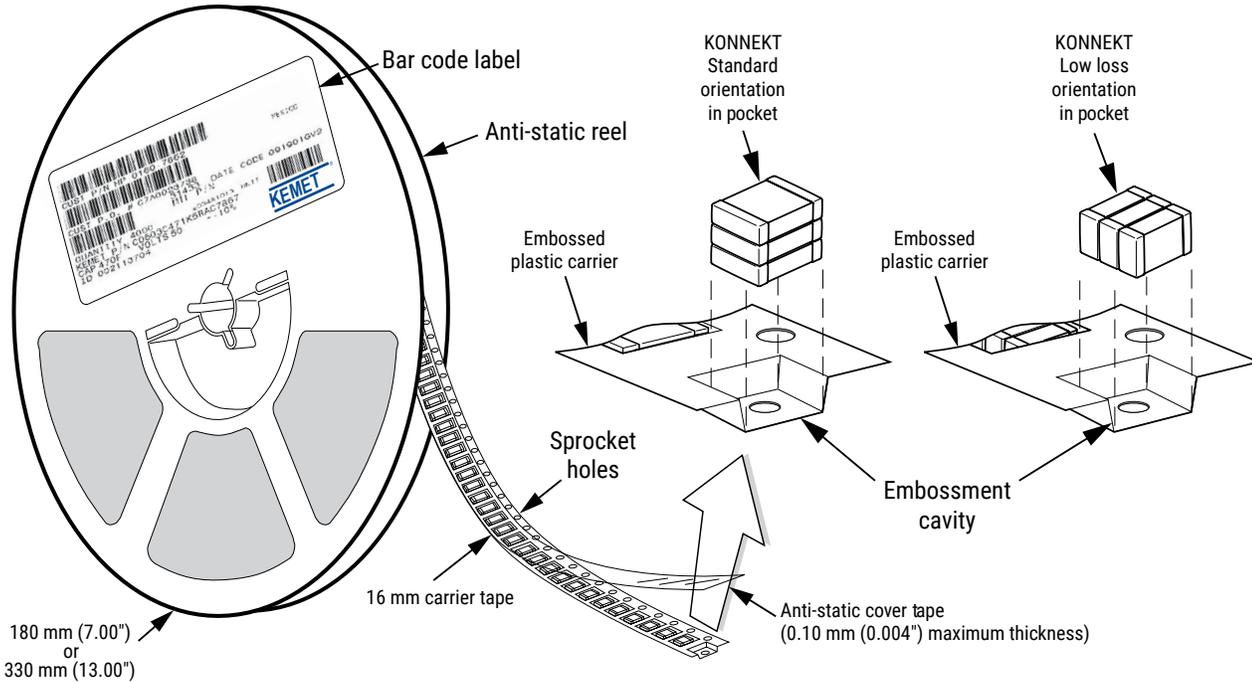


Table 4 – Carrier Tape Configuration, Embossed Plastic (mm)

EIA Case Size	Chip Number	Tape Size (W)*	Embossed Plastic	
			7" Reel	13" Reel
			Pitch (P ₁) ²	
KONNEKT 1812	2	16	8	8
	3	16	12	12

1. Refer to Figures 1 and 2 for W and P₁ carrier tape reference locations.
2. Refer to Tables 4 and 5 for tolerance specifications.

Figure 1 – Embossed (Plastic) Carrier Tape Dimensions

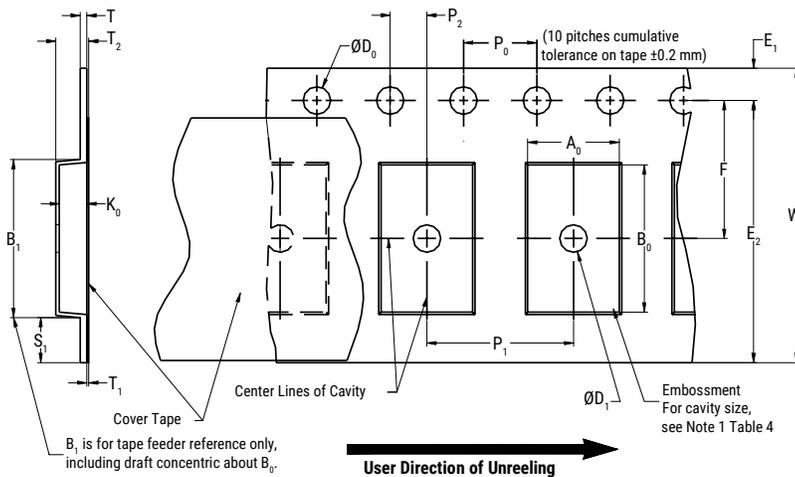


Table 5 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

Constant Dimensions – Millimeters (Inches)									
Tape Size	D ₀	D ₁ Minimum Note 1	E ₁	P ₀	P ₂	R Reference Note 2	S ₁ Minimum Note 3	T Maximum	T ₁ Maximum
16 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.5 (0.059)	1.75±0.10 (0.069±0.004)	4.0±0.10 (0.157±0.004)	2.0±0.05 (0.079±0.002)	30 (1.181)	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
Variable Dimensions – Millimeters (Inches)									
Tape Size	Pitch	B ₁ Maximum Note 4	E ₂ Minimum	F	P ₁	T ₂ Maximum	W Maximum	A ₀ , B ₀ & K ₀	
16 mm	Triple (12mm)	12.1 (0.476)	14.25 (0.561)	7.5±0.05 (0.138±0.002)	12.0±0.10 (0.157±0.004)	4.6 (0.181)	16.3 (0.642)	Note 5	

1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
2. The tape with or without components shall pass around R without damage (see Figure 6).
3. If S₁ < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Document 481 paragraph 4.3 (b)).
4. B₁ dimension is a reference dimension for tape feeder clearance only.
5. The cavity defined by A₀, B₀ and K₀ shall surround the component with sufficient clearance that:
 - (a) the component does not protrude above the top surface of the carrier tape.
 - (b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
 - (c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 3).
 - (d) lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 4)
 - (e) For KPS Series product, A₀ and B₀ are measured on a plane 0.3 mm above the bottom of the pocket.
 - (f) see Addendum in EIA Document 481 for standards relating to more precise taping requirements.

Packaging Information Performance Notes

- 1. Cover Tape Break Force:** 1.0 kg minimum.
- 2. Cover Tape Peel Strength:** The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
16 mm	0.1 to 1.3 Newton (10 to 130 gf)

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300±10 mm/minute.

- 3. Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. Refer to EIA Standards 556 and 624.

Figure 2 – Maximum Component Rotation

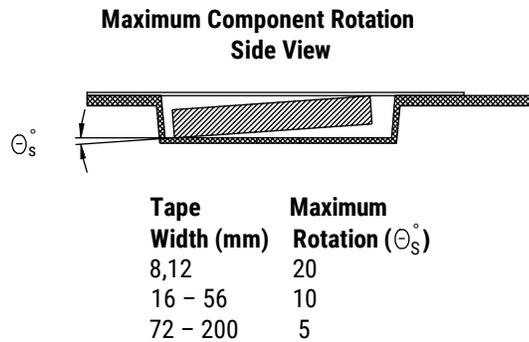
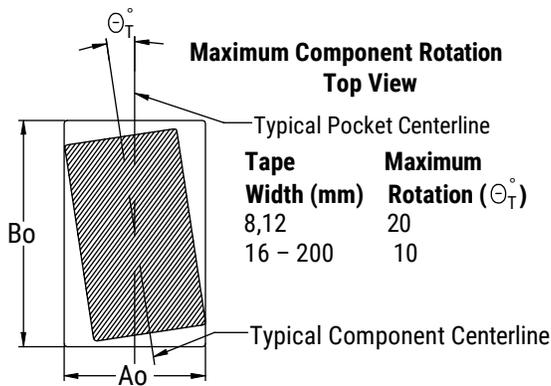


Figure 3 – Maximum Lateral Movement

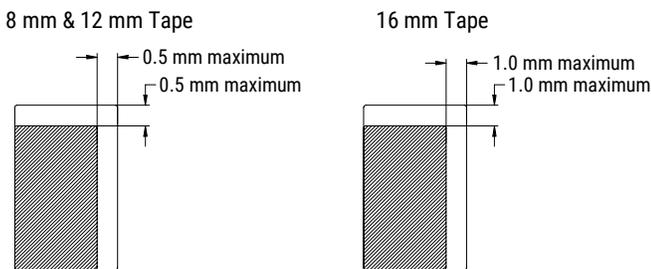


Figure 4 – Bending Radius

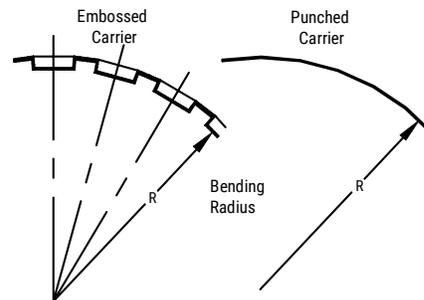
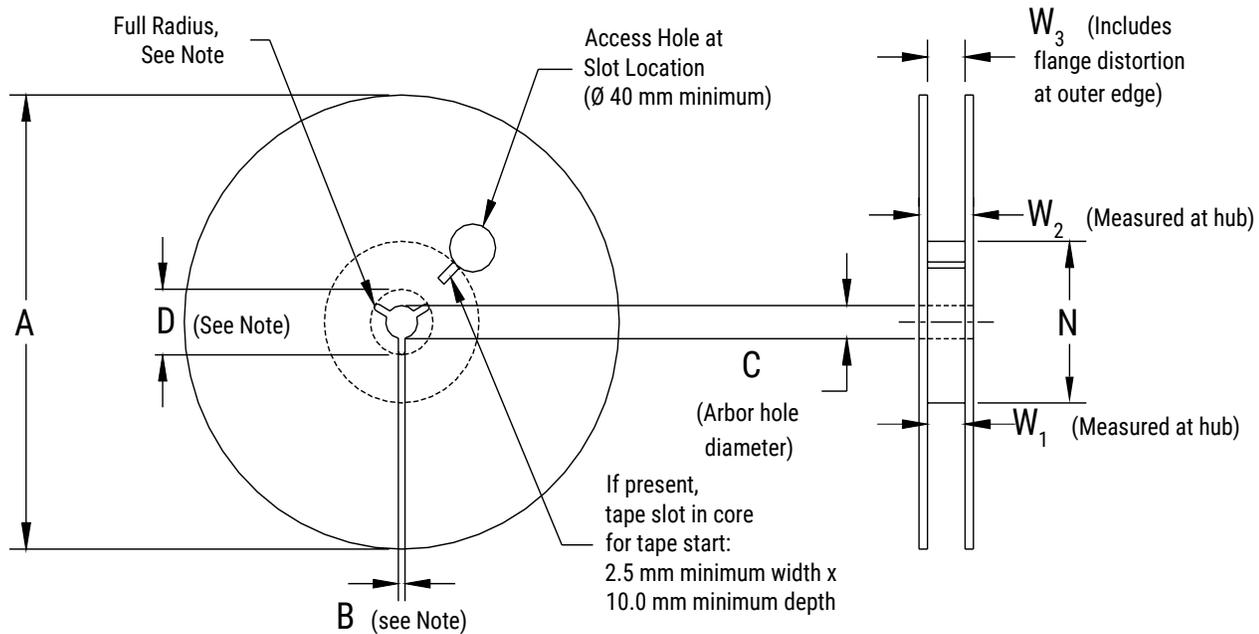


Figure 5 – Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

Table 6 – Reel Dimensions

Metric will govern

Constant Dimensions – Millimeters (Inches)				
Tape Size	A	B Minimum	C	D Minimum
16 mm	178±0.20 (7.008±0.008) or 330±0.20 (13.000±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)
Variable Dimensions – Millimeters (Inches)				
Tape Size	N Minimum See Note 2, Tables 2-3	W_1	W_2 Maximum	W_3
16 mm	50 (1.969)	16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)	Shall accommodate tape width without interference

Figure 6 – Tape Leader & Trailer Dimensions

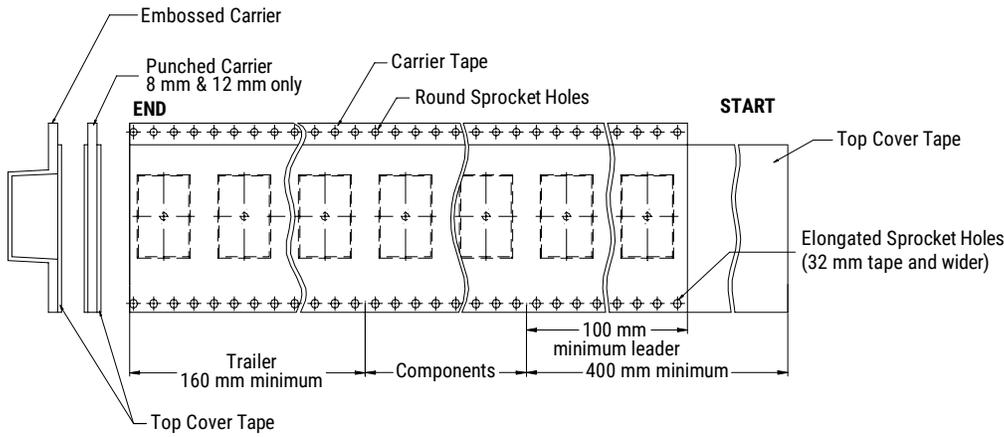
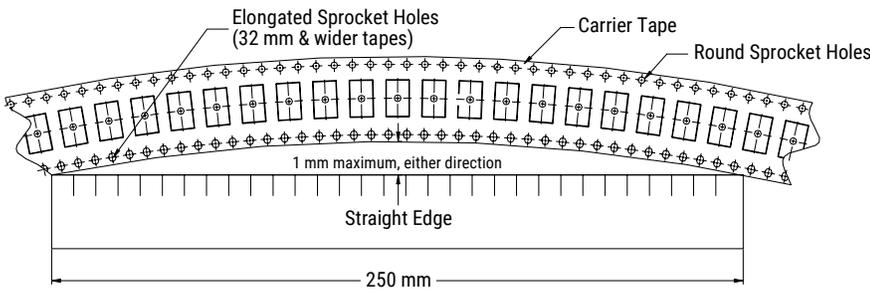


Figure 7 – Maximum Camber



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Although KEMET designs and manufactures its products to the most stringent quality and safety standards, given the current state of the art, isolated component failures may still occur. Accordingly, customer applications which require a high degree of reliability or safety should employ suitable designs or other safeguards (such as installation of protective circuitry or redundancies) in order to ensure that the failure of an electrical component does not result in a risk of personal injury or property damage.

Although all product-related warnings, cautions and notes must be observed, the customer should not assume that all safety measures are indicated or that other measures may not be required.

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